

AAA3528SEEZGGVBDS

3.5 x 2.8 mm Surface Mount LED Lamp



DESCRIPTIONS

- The Hyper Red source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode
- The Green source color devices are made with InGaN Light Emitting Diode
- The Blue source color devices are made with InGaN Light Emitting Diode
- · Electrostatic discharge and power surge could damage the LEDs
- It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs
- · All devices, equipments and machineries must be electrically grounded

FEATURES

- · Suitable for all SMD assembly and solder process
- · Available on tape and reel
- Package: 2000pcs / reel
- Moisture sensitivity level: 3
- · Halogen-free
- RoHS compliant

APPLICATIONS

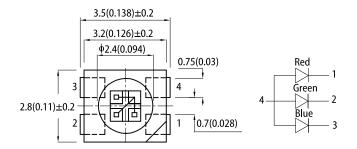
- Backlight
- · Status indicator
- · Home and smart appliances
- · Wearable and portable devices
- · Healthcare applications

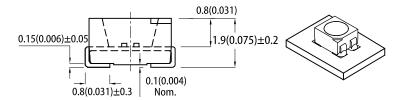
ATTENTION

Observe precautions for handling electrostatic discharge sensitive devices



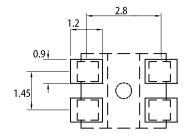
PACKAGE DIMENSIONS





RECOMMENDED SOLDERING PATTERN

(units: mm; tolerance: \pm 0.1)



- 1. All dimensions are in millimeters (inches)
- 2. Tolerance is ±0.25(0.01") unless otherwise noted.

 3. The specifications, characteristics and technical data described in the datasheet are subject to
- change without prior notice.

 The device has a single mounting surface. The device must be mounted according to the specifications

SELECTION GUIDE

Part Number	Emitting Color (Material)	Lens Type	Iv (mcd) @ 20mA [2]		Viewing Angle [1]	
			Min.	Тур.	201/2	
	Hyper Red (AlGalnP)		120	220		
AAA3528SEEZGGVBDS	Green (InGaN)	Water Clear	1000	1600	120°	
	■ Blue (InGaN)		200	330		

- 1. 61/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value 2. Luminous intensity / luminous flux: +/-15%.
- 3. Luminous intensity value is traceable to CIE127-2007 standards.





ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Parameter	Comple at	Freithing Colon	Value		11-14	
Parameter	Symbol	Emitting Color	Тур.	Max.	Unit	
Wavelength at Peak Emission I _F = 20mA	λ_{peak}	Hyper Red Green Blue	630 520 465	-	nm	
Dominant Wavelength I _F = 20mA	λ _{dom} ^[1]	Hyper Red Green Blue	621 525 470	-	nm	
Spectral Bandwidth at 50% Φ REL MAX I _F = 20mA	Δλ	Hyper Red Green Blue	20 35 22	-	nm	
Capacitance	С	Hyper Red Green Blue	25 100 100	-	pF	
Forward Voltage I _F = 20mA	V _F ^[2]	Hyper Red Green Blue	2.0 3.2 3.3	2.5 4.0 4.0	V	
Reverse Current (V _R = 5V)	I _R	Hyper Red Green Blue	-	10 50 50	μА	
Temperature Coefficient of λ_{peak} I_F = 20mA, -10°C \leq T \leq 85°C	$TC_{\lambda peak}$	Hyper Red Green Blue	0.13 0.05 0.04	-	nm/°C	
Temperature Coefficient of λ_{dom} I _F = 20mA, -10°C \leq T \leq 85°C	TC_{\lambdadom}	Hyper Red Green Blue	0.06 0.03 0.03	-	nm/°C	
Temperature Coefficient of V_F I_F = 20mA, -10°C \leq T \leq 85°C	TC _V	Hyper Red Green Blue	-1.9 -2.9 -2.9	-	mV/°C	

ABSOLUTE MAXIMUM RATINGS at T_A=25°C

	Symbol	Value			
Parameter		Hyper Red	Green	Blue	Unit
Power Dissipation	P _D	75	120	120	mW
Reverse Voltage	V_R	5	5	5	V
Junction Temperature	T _j	115	115	115	°C
Operating Temperature	T _{op}	-40 to +85			°C
Storage Temperature	T _{stg}	-40 to +85			°C
DC Forward Current	I _F	30	30	30	mA
Peak Forward Current	I _{FM} ^[1]	195	100	100	mA
Electrostatic Discharge Threshold (HBM)	-	3000	450	250	V
Thermal Resistance (Junction / Ambient)	R _{th JA} ^[2]	270	230	270	°C/W
Thermal Resistance (Junction / Solder point)	R _{th JS} ^[2]	140	100	150	°C/W

Notes:
1. 1/10Duty Cycle, 0.1ms Pulse Width.
2. R_{In. Ja}, R_{In. Ja} Results from mounting on PC board FR4 (pad size≥16 mm² per pad).
3. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.



Notes:

1. The dominant wavelength (λd) above is the setup value of the sorting machine. (Tolerance λd: ±1nm.)

2. Forward voltage: ±0.1V.

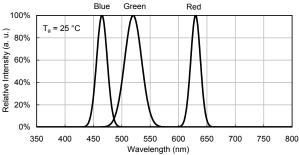
3. Wavelength value is traceable to CIE127-2007 standards.

4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

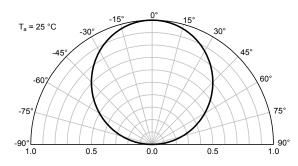


TECHNICAL DATA

RELATIVE INTENSITY vs. WAVELENGTH



SPATIAL DISTRIBUTION



HYPER RED

Forward Voltage 50 T_a = 25 °C 40 Forward current (mA) 30 20 10

1.9

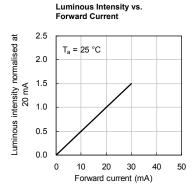
Forward voltage (V)

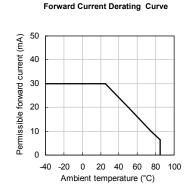
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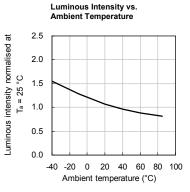
2.1 2.3

1.5

Forward Current vs.

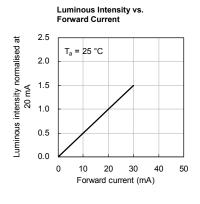


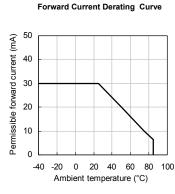


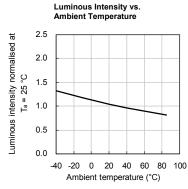


GREEN

Forward Current vs. Forward Voltage 50 T_a = 25 °C 40 Forward current (mA) 20 10 3.0 2.0 2.5 3.5 4.0 4.5 Forward voltage (V)

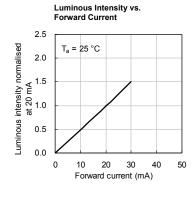


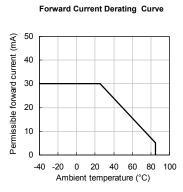


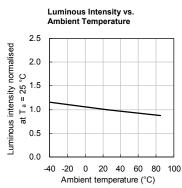


BLUE

Forward Current vs. Forward Voltage 50 T_a = 25 °C 40 Forward current (mA) 30 20 n 2.4 2.8 3.2 3.6 Forward voltage (V)

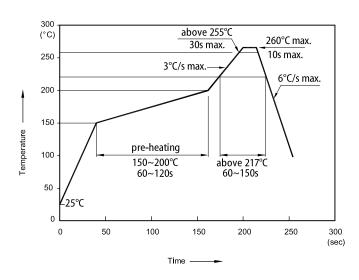






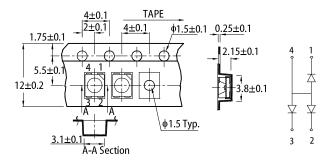


REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS

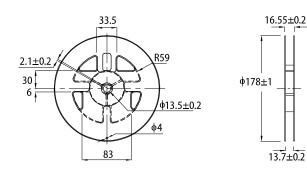


- 1. Don't cause stress to the LEDs while it is exposed to high temperature.
 2. The maximum number of reflow soldering passes is 2 times.
 3. Reflow soldering is recommended. Other soldering methods are not recommended as they might

TAPE SPECIFICATIONS (units:mm)



REEL DIMENSION (units: mm)



HANDLING PRECAUTIONS

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

2. Do not directly touch or handle the silicone lens

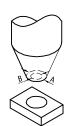
- 1. Handle the component along the side surfaces by using forceps or appropriate tools.
- surface. It may damage the internal circuitry.
- 3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.





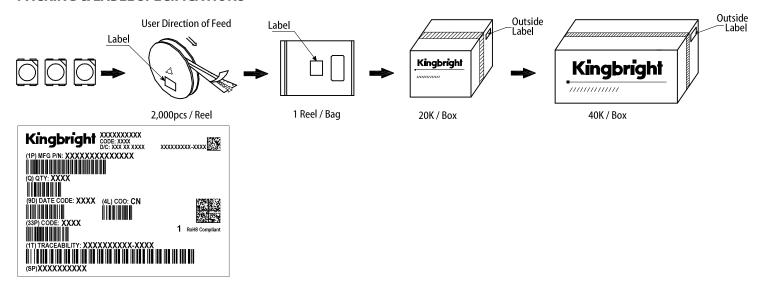


- 4-1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4-2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4-3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.
- 5. As silicone encapsulation is permeable to gases, some corrosive substances such as H₂S might corrode silver plating of lead frame. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.





PACKING & LABEL SPECIFICATIONS



- The information included in this document reflects representative usage scenarios and is intended for technical reference only.

 The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
- When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.

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